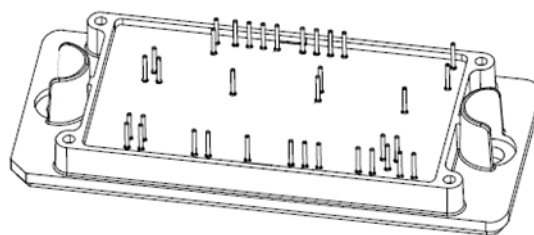


### Electrical Features

- Neutral Point Clamped Three-Level Inverter Module
- Low Inductive Layout
- Solderable Pins
- Higher System Efficiency
- Reduced Cooling Requirements
- Low Conduction Losses Over Temperature



### Typical Applications

- Solar Inverters
- Uninterruptable Power Supplies Systems

**Table 1 Absolute Maximum Ratings (Ta=25°C)**

Outer IGBT(Q1,Q4)							
Maximum Rated Values							
Symbol	Item	Conditions	Rating	Unit			
V <sub>CES</sub>	Collector-emitter voltage	T <sub>vj</sub> =25°C	650	V			
V <sub>GES</sub>	Gate-emitter voltage	-	±20	V			
I <sub>C</sub>	Continuous Collector Current	T <sub>C</sub> =80°C, T <sub>vj</sub> =175°C	270	A			
I <sub>CP</sub>	Pulsed Collector Current	T <sub>vj</sub> =175°C	810	A			
T <sub>vj</sub>	Junction Temperature	-	-40 to +175	°C			
Characteristics Values							
Symbol	Item	Conditions	Values			Unit	
IGBT			Min.	Typ.	Max.		
I <sub>CES</sub>	Collector-emitter cut-off current	V <sub>CE</sub> =650V, V <sub>GE</sub> =0V, T <sub>vj</sub> =25°C	-	-	100	uA	
I <sub>GES</sub>	Gate leakage current	V <sub>CE</sub> =0V, V <sub>GE</sub> =20V, T <sub>vj</sub> =25°C	-	-	100	nA	
V <sub>(BR)CES</sub>	Collector-emitter voltage	V <sub>GE</sub> =0V, T <sub>vj</sub> =25°C	650	-	-	V	
V <sub>GE(th)</sub>	Gate-emitter threshold voltage	I <sub>C</sub> =8mA, V <sub>CE</sub> =V <sub>GE</sub> , T <sub>vj</sub> =25°C	3.5	4.18	6.4	V	
V <sub>CEsat</sub>	Collector-emitter saturation voltage	I <sub>C</sub> =450A V <sub>GE</sub> =15V	T <sub>vj</sub> =25°C	-	1.42		3
			T <sub>vj</sub> =125°C	-	1.59		-
			T <sub>vj</sub> =150°C	-	-	-	
C <sub>ies</sub>	Input capacitance	V <sub>CE</sub> =20V, V <sub>GE</sub> =0V f=10KHz, T <sub>vj</sub> =25°C	-	-	-	nF	
C <sub>oes</sub>	Output capacitance		-	-	-		
C <sub>res</sub>	Reverse transfer capacitance		-	-	-		
Q <sub>G</sub>	Gate charge	V <sub>GE</sub> =-8/+15V	-	0.63	-	uC	

$t_{d(on)}$	Turn-on delay time	$V_{CE}=400V,$ $I_C=450A,$ $V_{GE}=-8V/+15V,$ $R_{G(on)}=15\ \Omega,$ $R_{G(off)}=20\ \Omega$	$T_{vj}=25^\circ C$	-	84	-	us
			$T_{vj}=125^\circ C$	-	68	-	
			$T_{vj}=150^\circ C$	-		-	
$t_r$	Rise time		$T_{vj}=25^\circ C$	-	136	-	
			$T_{vj}=125^\circ C$	-	136	-	
			$T_{vj}=150^\circ C$	-		-	
$t_{d(off)}$	Turn-off delay time		$T_{vj}=25^\circ C$	-	746	-	
			$T_{vj}=125^\circ C$	-	790	-	
			$T_{vj}=150^\circ C$	-		-	
$t_f$	Fall time	$T_{vj}=25^\circ C$	-	128	-		
		$T_{vj}=125^\circ C$	-	132	-		
		$T_{vj}=150^\circ C$	-		-		
$E_{on}$	Turn-on energy (per pulse)	$V_{CE}=400V,$ $I_C=450A,$ $V_{GE}=-8V/+15V,$ $R_{G(on)}=15\ \Omega,$ $R_{G(off)}=20\ \Omega$	$T_{vj}=25^\circ C$	-	7.3	-	mJ
			$T_{vj}=125^\circ C$	-	10.3	-	
			$T_{vj}=150^\circ C$	-		-	
$E_{off}$	Turn-off energy (per pulse)		$T_{vj}=25^\circ C$	-	31.6	-	
			$T_{vj}=125^\circ C$	-	33.6	-	
			$T_{vj}=150^\circ C$	-		-	
SC data	Short-circuit current	$V_{CC}=400V, V_{GE}\leq 15V, T_{vj}=150^\circ C,$ $t_p\leq 10\mu s$	-	-	-	A	
$R_{thJC}$	Thermal resistance, chip to case	per IGBT/ $\lambda_{grease}=2.8W/(m\cdot K)$	-		-	K/W	
$R_{thJH}$	Thermal resistance, chip to heatsink		-		-	K/W	

**Neutral Point Diode(D5,D6)**

**Maximum Rated Values**

Symbol	Item	Conditions	Rating	Unit
$V_{RRM}$	Repetitive peak reverse voltage	$T_{vj}=25^\circ C$	650	V
$I_F$	Forward current, DC	$T_C=80^\circ C, T_{vj}=175^\circ C$	230	A
$I_{FRM}$	Repetitive peak forward current	$T_{vj}=175^\circ C$	690	A
$T_{vj}$	Junction Temperature	-	-40 to +175	$^\circ C$

**Characteristic Values**

			Min.	Typ.	Max.		
$V_F$	Continuous forward voltage	$I_F=450A$ $V_{GE}=0V$	$T_{vj}=25^\circ C$	-	1.55	3	V
			$T_{vj}=125^\circ C$	-	1.59	-	
			$T_{vj}=150^\circ C$	-		-	
$I_{RM}$	Peak reverse recovery current	$V_{CE}=400V,$ $I_C=450A,$ $V_{GE}=-8V/+15V,$ $R_{G(on)}=15\ \Omega,$ $R_{G(off)}=20\ \Omega$	$T_{vj}=25^\circ C$	-	191	-	A
			$T_{vj}=125^\circ C$	-	219	-	
			$T_{vj}=150^\circ C$	-		-	
$t_{rr}$	Reverse recovery time		$T_{vj}=25^\circ C$	-	64	-	us
			$T_{vj}=125^\circ C$	-	72	-	
			$T_{vj}=150^\circ C$	-		-	

Q <sub>r</sub>	Recovered charge		T <sub>vj</sub> =25°C	-	24.7	-	μC
			T <sub>vj</sub> =125°C	-	34.5	-	
			T <sub>vj</sub> =150°C	-		-	
E <sub>rec</sub>	Reverse recovery energy		T <sub>vj</sub> =25°C	-	10.5	-	mJ
			T <sub>vj</sub> =125°C	-	14.3	-	
			T <sub>vj</sub> =150°C	-		-	
R <sub>thJC</sub>	Thermal resistance, chip to case	per diode/ λgrease=2.8W/(m·K)	-		-	K/W	
R <sub>thJH</sub>	Thermal resistance, chip to heatsink		-		-	K/W	
T <sub>vjop</sub>	Temperature under switching conditions		-40		150	°C	

**Inner IGBT(Q2,Q3)**

**Maximum Rated Values**

Symbol	Item	Conditions	Rating	Unit
V <sub>CES</sub>	Collector-emitter voltage	T <sub>vj</sub> =25°C	650	V
V <sub>GES</sub>	Gate-emitter voltage	-	±20	V
I <sub>C</sub>	Continuous Collector Current	T <sub>C</sub> =80°C, T <sub>vj</sub> =175°C	293	A
I <sub>CP</sub>	Pulsed Collector Current	T <sub>vj</sub> =175°C	880	A
T <sub>vj</sub>	Junction Temperature	-	-40 to +175	°C

**Characteristics Values**

Symbol	Item	Conditions	Values			Unit	
			Min.	Typ.	Max.		
IGBT							
I <sub>CES</sub>	Collector-emitter cut-off current	V <sub>CE</sub> =650V, V <sub>GE</sub> =0V, T <sub>vj</sub> =25°C	-	-	100	uA	
I <sub>GES</sub>	Gate leakage current	V <sub>CE</sub> =0V, V <sub>GE</sub> =20V, T <sub>vj</sub> =25°C	-	-	100	nA	
V <sub>(BR)CES</sub>	Collector-emitter voltage	V <sub>GE</sub> =0V, T <sub>vj</sub> =25°C	650	-	-	V	
V <sub>GE(th)</sub>	Gate-emitter threshold voltage	I <sub>C</sub> =8mA, V <sub>CE</sub> =V <sub>GE</sub> , T <sub>vj</sub> =25°C	3.5	4.04	6.4	V	
V <sub>CEsat</sub>	Collector-emitter saturation voltage	I <sub>C</sub> =450A V <sub>GE</sub> =15V	T <sub>vj</sub> =25°C	-	1.26		3
			T <sub>vj</sub> =125°C	-	1.34		-
			T <sub>vj</sub> =150°C	-		-	
C <sub>ies</sub>	Input capacitance	V <sub>CE</sub> =20V, V <sub>GE</sub> =0V f=10KHZ, T <sub>vj</sub> =25°C	-		-	nF	
C <sub>oes</sub>	Output capacitance		-		-		
C <sub>res</sub>	Reverse transfer capacitance		-		-		
Q <sub>G</sub>	Gate charge	V <sub>GE</sub> =-8/+15V	-	0.89	-	uC	

t <sub>d(on)</sub>	Turn-on delay time	V <sub>CE</sub> =400V, I <sub>C</sub> =450A, V <sub>GE</sub> =-8V/+15V, R <sub>G(on)</sub> =20 Ω, R <sub>G(off)</sub> =20 Ω	T <sub>vj</sub> =25°C	-	227	-	us	
			T <sub>vj</sub> =125°C	-	206	-		
			T <sub>vj</sub> =150°C	-		-		
t <sub>r</sub>	Rise time		T <sub>vj</sub> =25°C	-	194	-		
			T <sub>vj</sub> =125°C	-	205	-		
			T <sub>vj</sub> =150°C	-		-		
t <sub>d(off)</sub>	Turn-off delay time		T <sub>vj</sub> =25°C	-	1552	-		
			T <sub>vj</sub> =125°C	-	1608	-		
			T <sub>vj</sub> =150°C	-		-		
t <sub>f</sub>	Fall time	T <sub>vj</sub> =25°C	-	166	-			
		T <sub>vj</sub> =125°C	-	173	-			
		T <sub>vj</sub> =150°C	-		-			
E <sub>on</sub>	Turn-on energy (per pulse)	V <sub>CE</sub> =400V, I <sub>C</sub> =450A, V <sub>GE</sub> =-8V/+15V, R <sub>G(on)</sub> =20 Ω, R <sub>G(off)</sub> =20 Ω	T <sub>vj</sub> =25°C	-	14.2	-	mJ	
			T <sub>vj</sub> =125°C	-	17.9	-		
			T <sub>vj</sub> =150°C	-		-		
E <sub>off</sub>	Turn-off energy (per pulse)		T <sub>vj</sub> =25°C	-	45.6	-		
			T <sub>vj</sub> =125°C	-	49.3	-		
			T <sub>vj</sub> =150°C	-		-		
SC data	Short-circuit current		V <sub>CC</sub> =400V, V <sub>GE</sub> ≤15V, T <sub>vj</sub> =150°C, t <sub>p</sub> ≤10μs	-	-	-	-	A
R <sub>thJC</sub>	Thermal resistance, chip to case		per IGBT/ λ <sub>grease</sub> =2.8W/(m·K)	-			-	K/W
R <sub>thJH</sub>	Thermal resistance, chip to heatsink			-			-	K/W
<b>Inverse Diode(D1,D2, D3,D4)</b>								
<b>Maximum Rated Values</b>								
Symbol	Item	Conditions			Rating	Unit		
V <sub>RRM</sub>	Repetitive peak reverse voltage	T <sub>vj</sub> =25°C			650	V		
I <sub>F</sub>	Forward current,DC	T <sub>C</sub> =80°C, T <sub>vj</sub> =175°C			188	A		
I <sub>FRM</sub>	Repetitive peak forward current	T <sub>vj</sub> =175°C			563	A		
I <sup>2</sup> t	I <sup>2</sup> t-value	V <sub>R</sub> =0V, t <sub>p</sub> =10ms, T <sub>vj</sub> =125°C			1800	A <sup>2</sup> s		
T <sub>vj</sub>	Junction Temperature	-			-40 to +175	°C		
<b>Characteristic Values</b>				Min.	Typ.	Max.		
V <sub>F</sub>	Continuous forward voltage	I <sub>F</sub> =450A V <sub>GE</sub> =0V	T <sub>vj</sub> =25°C	-	1.73	3		
			T <sub>vj</sub> =125°C	-	1.94	-		
			T <sub>vj</sub> =150°C	-		-		
I <sub>RM</sub>	Peak reverse recovery current	V <sub>CE</sub> =400V, I <sub>C</sub> =450A, V <sub>GE</sub> =-8V/+15V,	T <sub>vj</sub> =25°C	-	105	-		
			T <sub>vj</sub> =125°C	-	123	-		
			T <sub>vj</sub> =150°C	-		-		
t <sub>rr</sub>	Reverse recovery time	R <sub>G(on)</sub> =20 Ω, R <sub>G(off)</sub> =20 Ω	T <sub>vj</sub> =25°C	-	52	-		
			T <sub>vj</sub> =125°C	-	56	-		
			T <sub>vj</sub> =150°C	-		-		

Q <sub>r</sub>	Recovered charge		T <sub>vj</sub> =25°C	-	10.8	-	μC
			T <sub>vj</sub> =125°C	-	16.6	-	
			T <sub>vj</sub> =150°C	-		-	
E <sub>rec</sub>	Reverse recovery energy		T <sub>vj</sub> =25°C	-	5.5	-	mJ
			T <sub>vj</sub> =125°C	-	6.7	-	
			T <sub>vj</sub> =150°C	-		-	
R <sub>thJC</sub>	Thermal resistance, chip to case	per diode/ λgrease=2.8W/(m·K)	-		-	K/W	
R <sub>thJH</sub>	Thermal resistance, chip to heatsink		-		-	K/W	
T <sub>vjop</sub>	Temperature under switching conditions		-40		150	°C	

### NTC Thermistor Characteristics

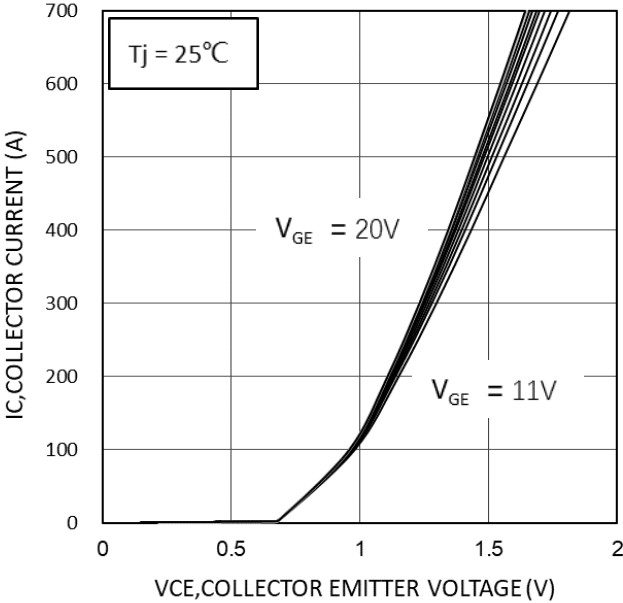
Symbol	Item	Conditions	Values			Unit
			Min.	Typ.	Max.	
R <sub>25</sub>	Rated resistance	T <sub>C</sub> =25°C	-	22	-	kΩ
ΔR/R	Deviation of resistance	T <sub>C</sub> =100°C, R <sub>100</sub> =1486Ω	-5	-	5	%
P <sub>25</sub>	Power dissipation	T <sub>C</sub> =25°C	-	-	20	mW
B <sub>25/50</sub>	B-constant	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15K))]$	-	3950	-	K
B <sub>25/80</sub>	B-constant	$R_2=R_{25}\exp[B_{25/80}(1/T_2-1/(298.15K))]$	-	-	-	
B <sub>25/100</sub>	B-constant	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15K))]$	-	3998	-	

### Module

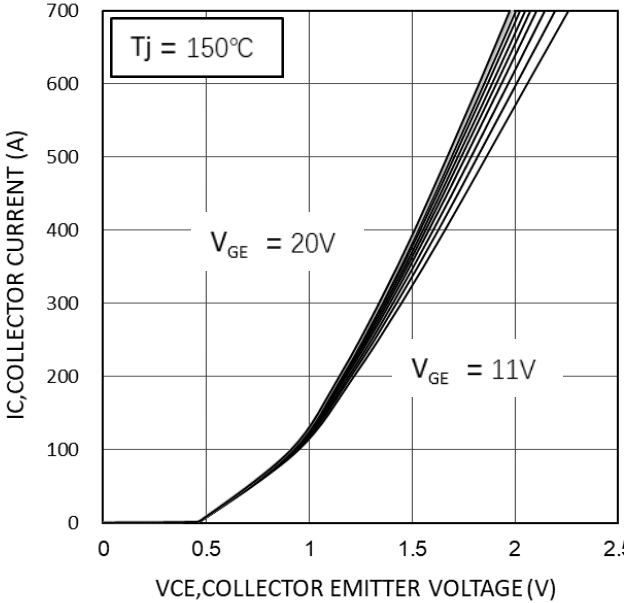
Symbol	Item	Conditions	Rating			Unit
V <sub>ISOL</sub>	Isolation voltage	Terminals to baseplate, RMS, f=50Hz, t=1min	4000			V
-	Material of module baseplate	-	Cu			-
T <sub>stg</sub>	Storage temperature	-	-40~125			°C
T <sub>op</sub>	Operating temperature	-	-40~150			°C
Symbol	Item	Conditions	Values			Unit
			Min.	Typ.	Max.	-
M	Mounting torque for module mounting	Screw M5	3.0	-	5.0	Nm
L <sub>sCE</sub>	Stray inductance module	-				nH
d <sub>Creep</sub>	Creepage distance	Terminal to terminal	-	13	-	mm
		Terminal to base plate	-	14.5	-	
d <sub>Clear</sub>	Clearance	Terminal to terminal	-	10	-	mm
		Terminal to base plate	-	12.5	-	
CTI	Comperative tracking index	-	≥600			
RTI	-	-	130			°C
Bd	Baseplate deflection	-			0.3	mm
m	Weight	-	-	176.5	-	g

Typical Characteristics  
IGBT Q1, Q4 And Diode D1, D4

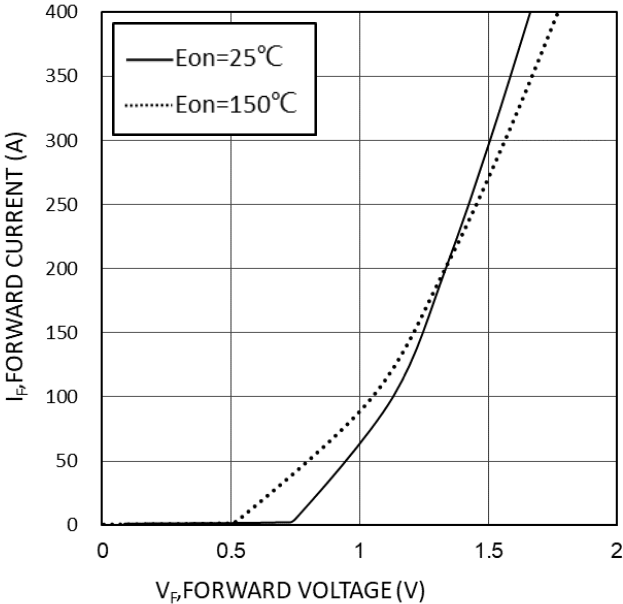
Typical Output Characteristics(25°C)



Typical Output Characteristics(125°C)

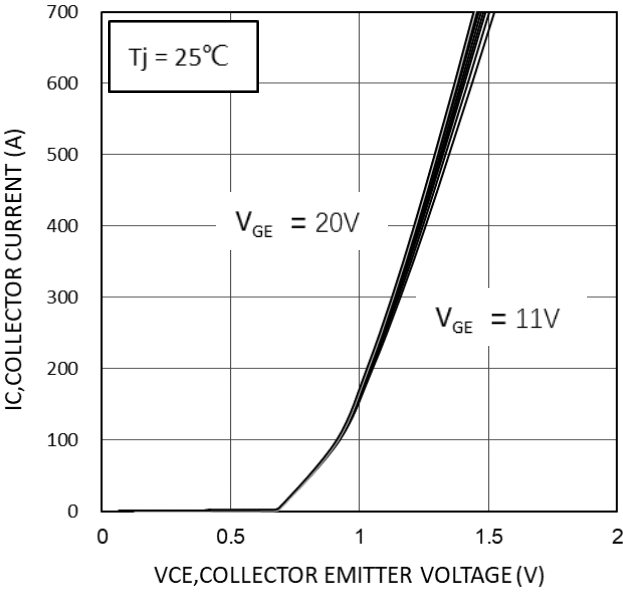


Body Diode Characteristics

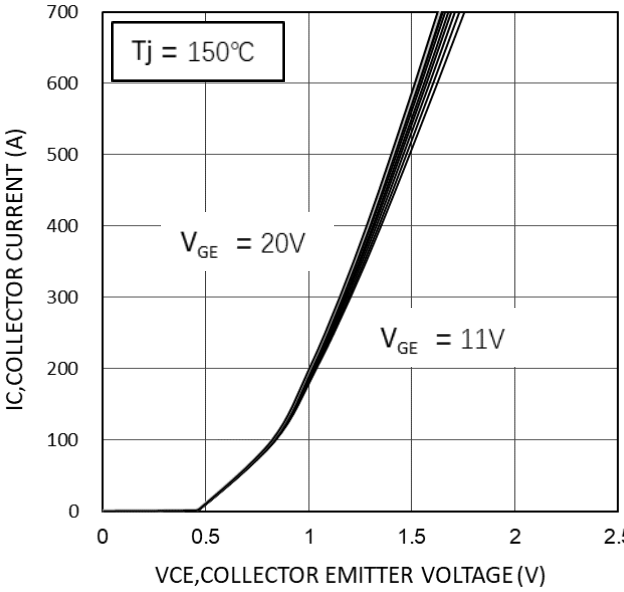


Typical Characteristics  
IGBT Q2, Q3 And Diode D2, D3

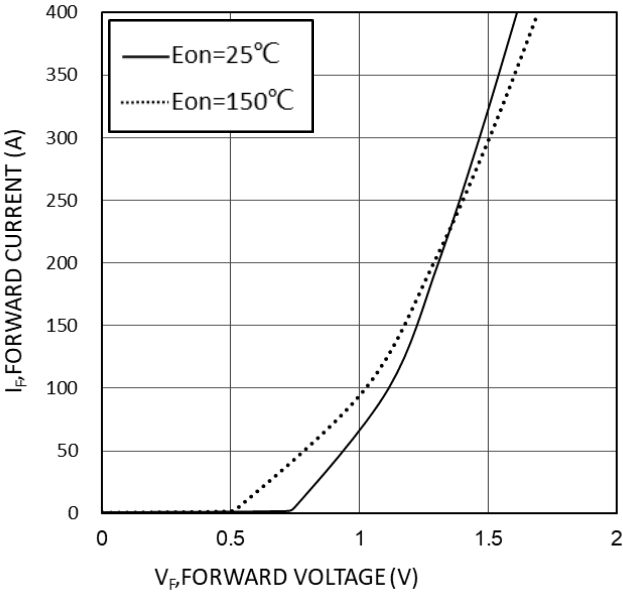
Typical Output Characteristics(25°C)



Typical Output Characteristics(125°C)

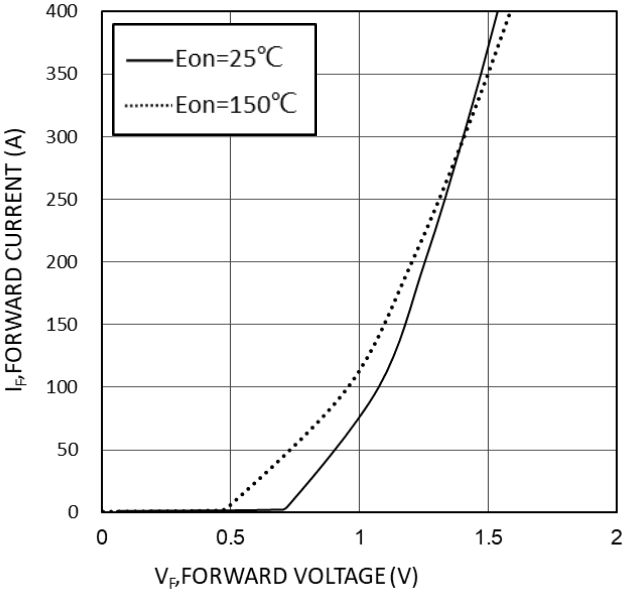


Body Diode Characteristics



Typical Characteristics  
Diode D5, D6

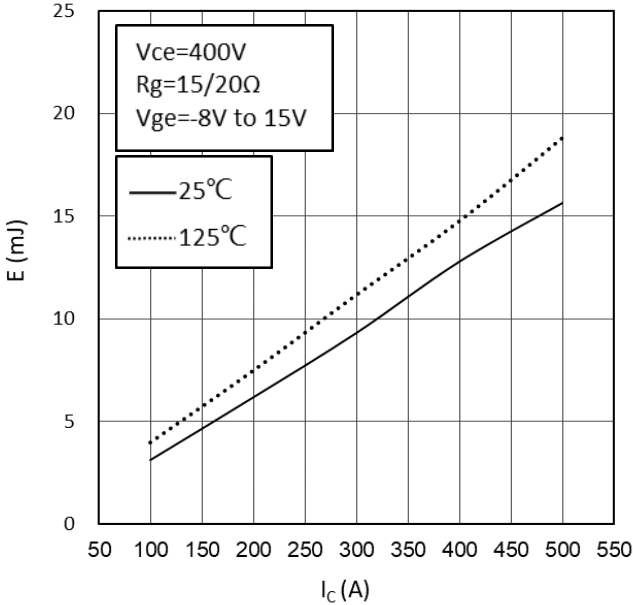
Diode Forward Characteristic



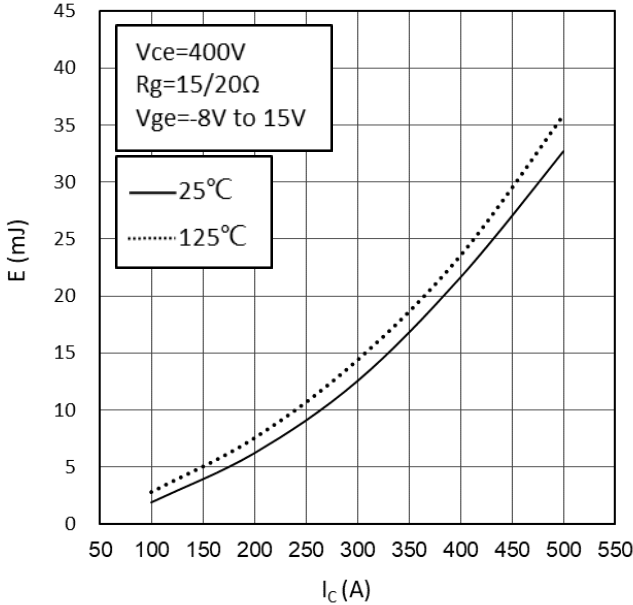


### Typical Characteristics IGBT Q1, Q4 And Diode D5, D6

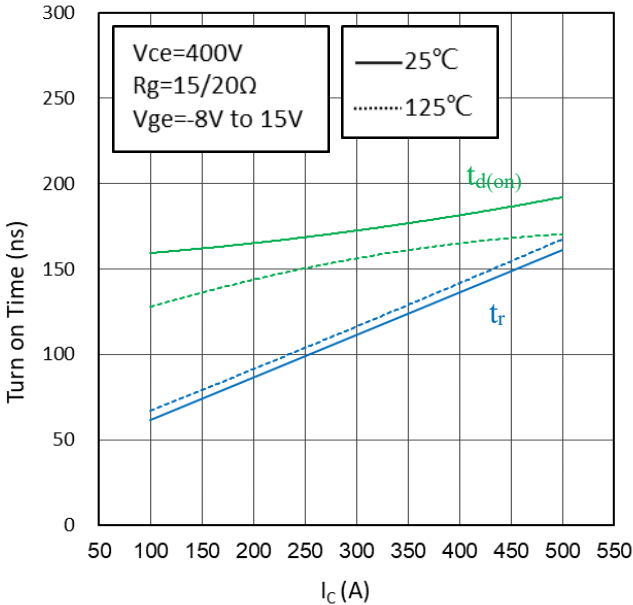
Typical Switching Loss Eon vs. IC



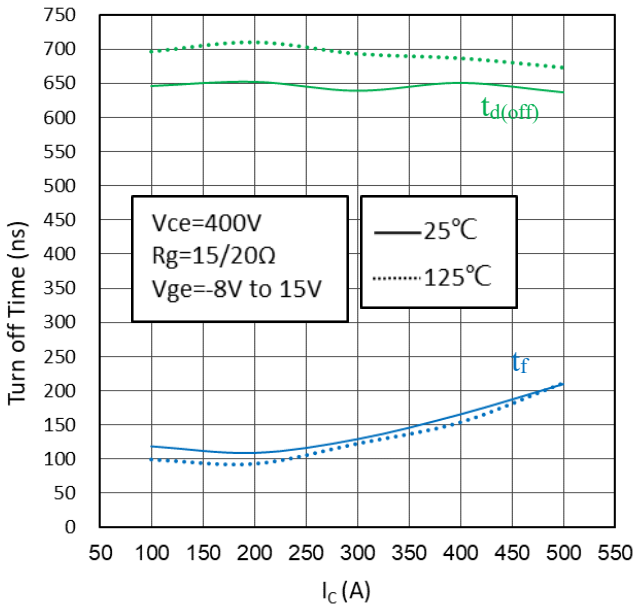
Typical Switching Loss Eoff vs. IC



Typical Switching Time Ton vs. IC

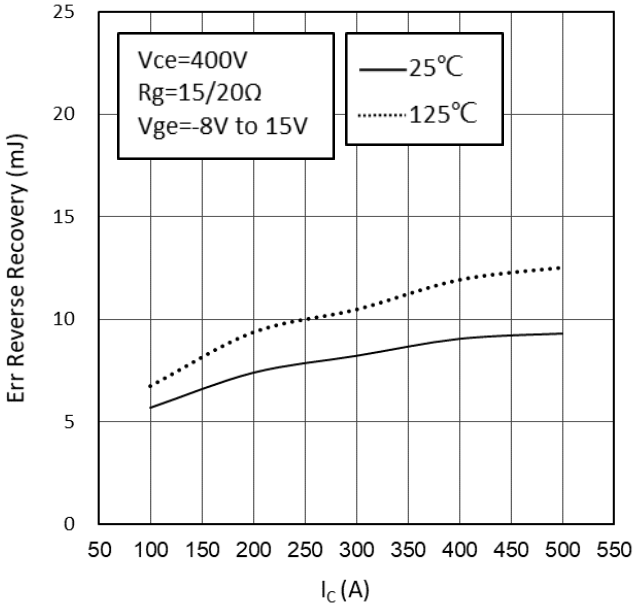


Typical Switching Time Toff vs. IC

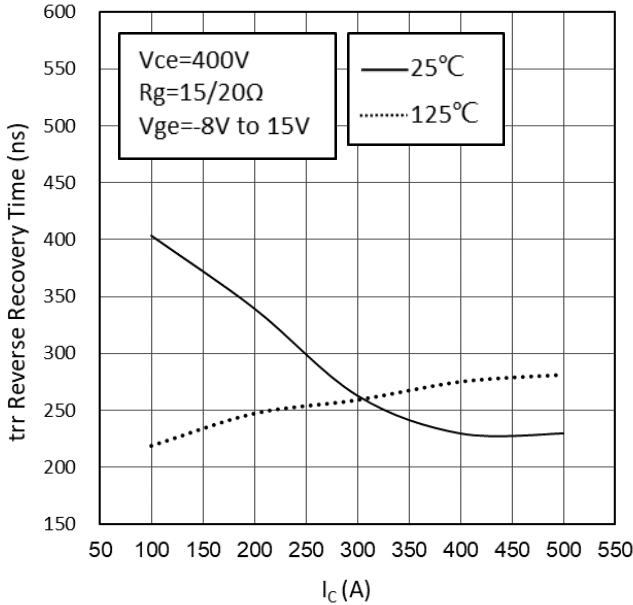


Typical Characteristics  
IGBT Q1, Q4 And Diode D5, D6

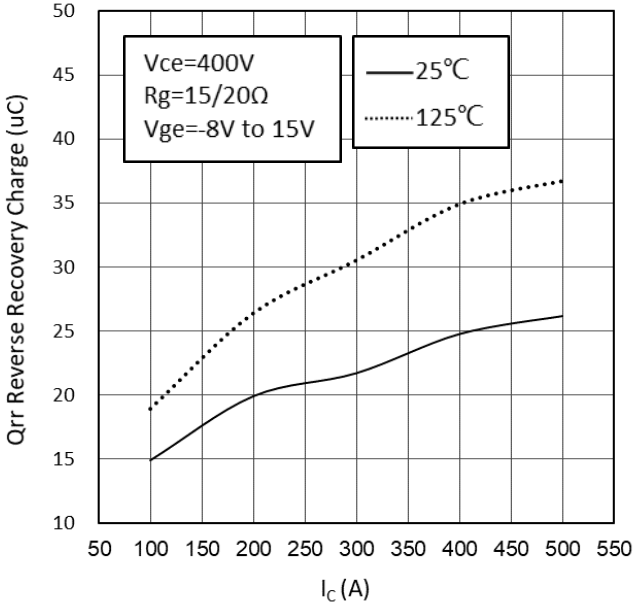
Typical Reverse Recovery Energy vs. IC



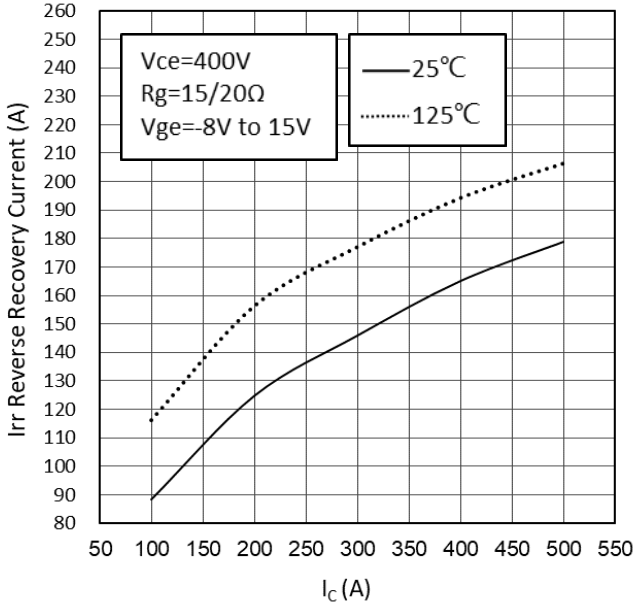
Typical Reverse Recovery Time vs. IC



Typical Reverse Recovery Charge vs. IC

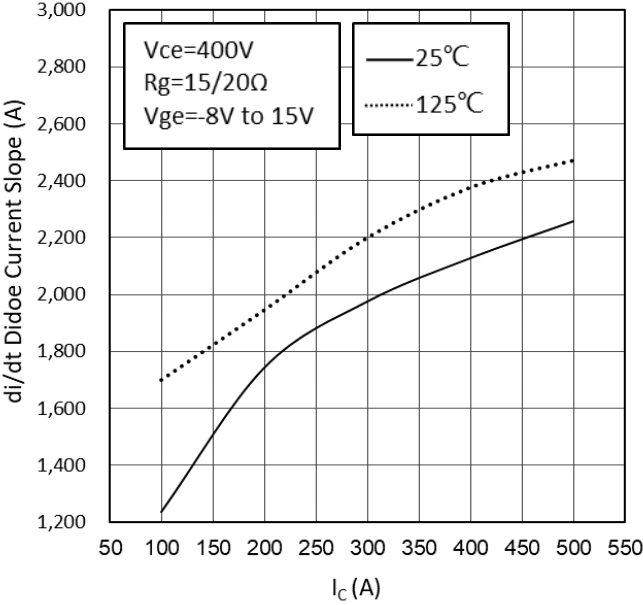


Typical Reverse Recovery Current vs. IC



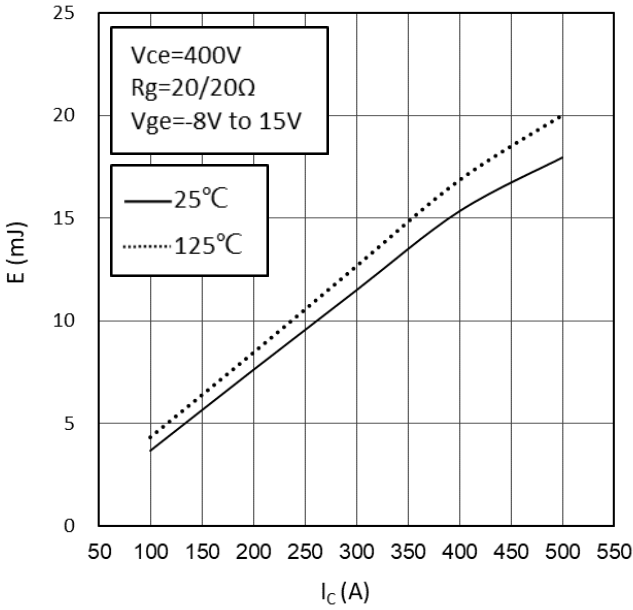
Typical Characteristics  
IGBT Q1, Q4 And Diode D5, D6

Typical di/dt vs. IC

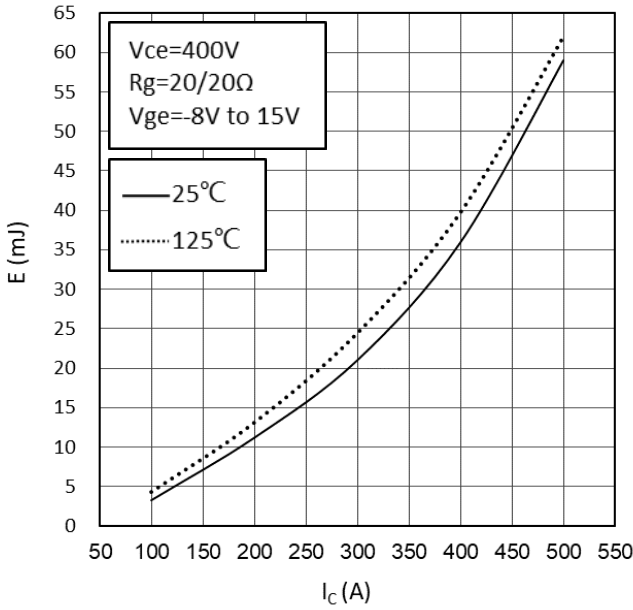


Typical Characteristics  
IGBT Q2, Q3 And Diode D1, D4

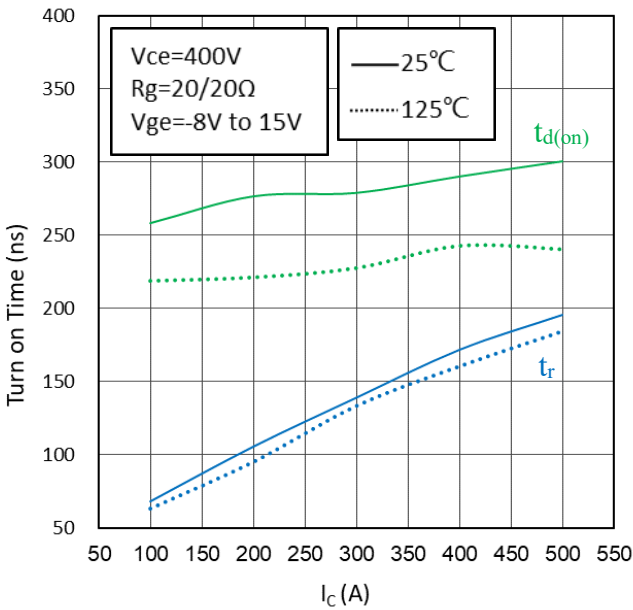
Typical Switching Loss Eon vs. IC



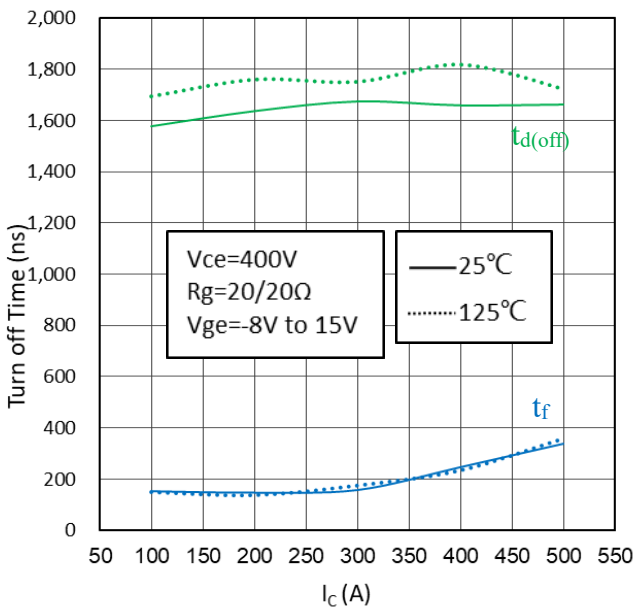
Typical Switching Loss Eoff vs. IC



Typical Switching Time Ton vs. IC

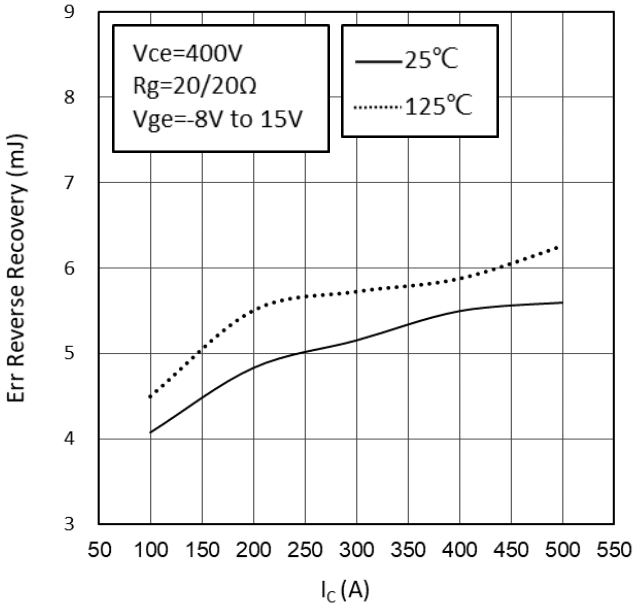


Typical Switching Time Toff vs. IC

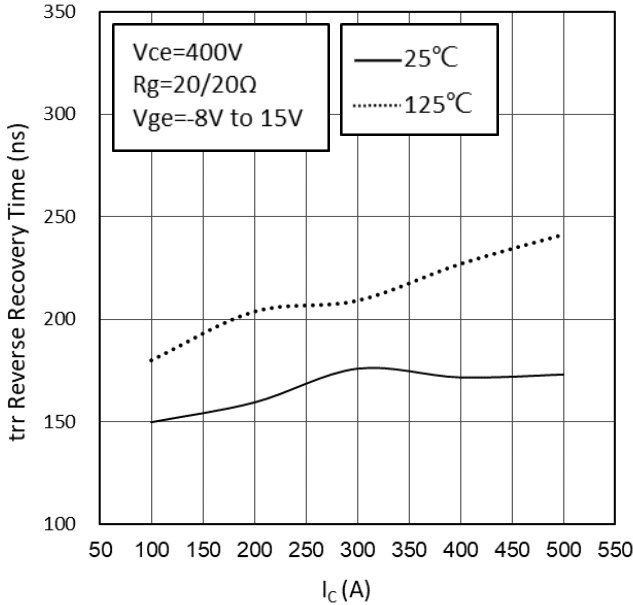


Typical Characteristics  
IGBT Q2, Q3 And Diode D1, D4

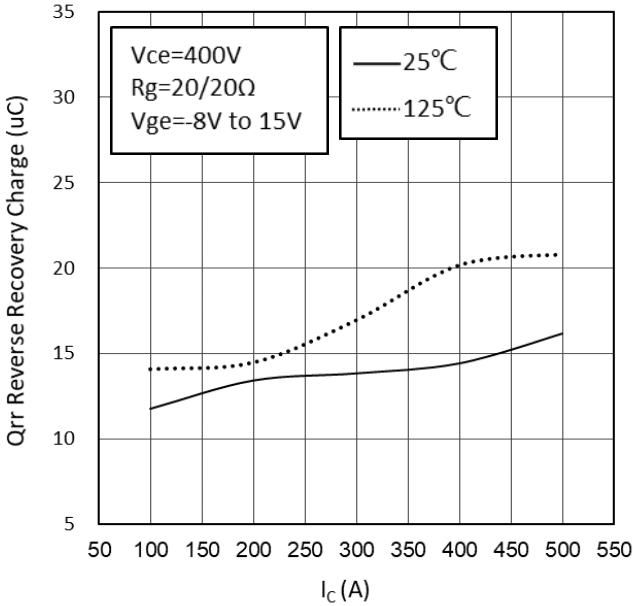
Typical Reverse Recovery Energy vs. IC



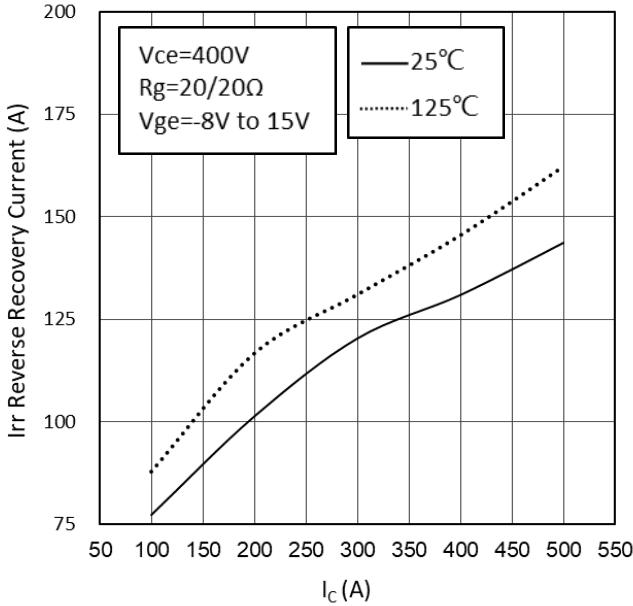
Typical Reverse Recovery Time vs. IC



Typical Reverse Recovery Charge vs. IC

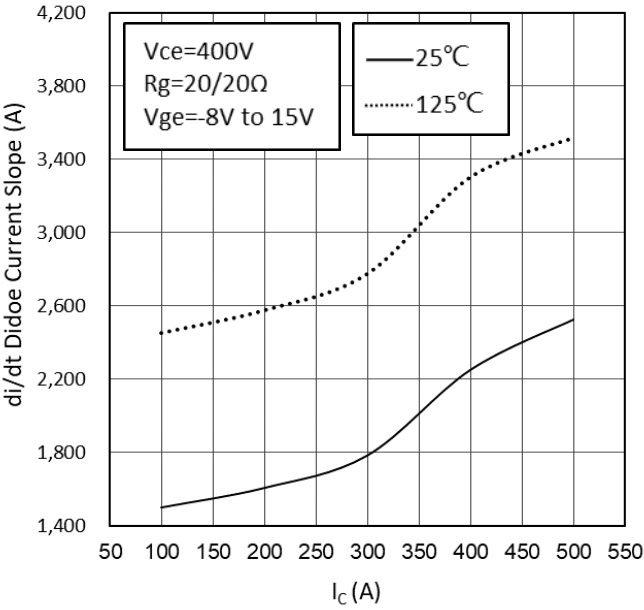


Typical Reverse Recovery Current vs. IC

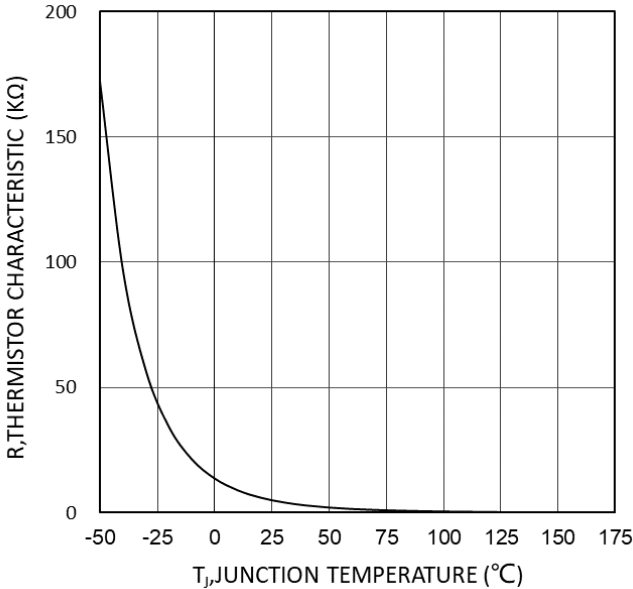


### Typical Characteristics IGBT Q2, Q3 And Diode D1, D4

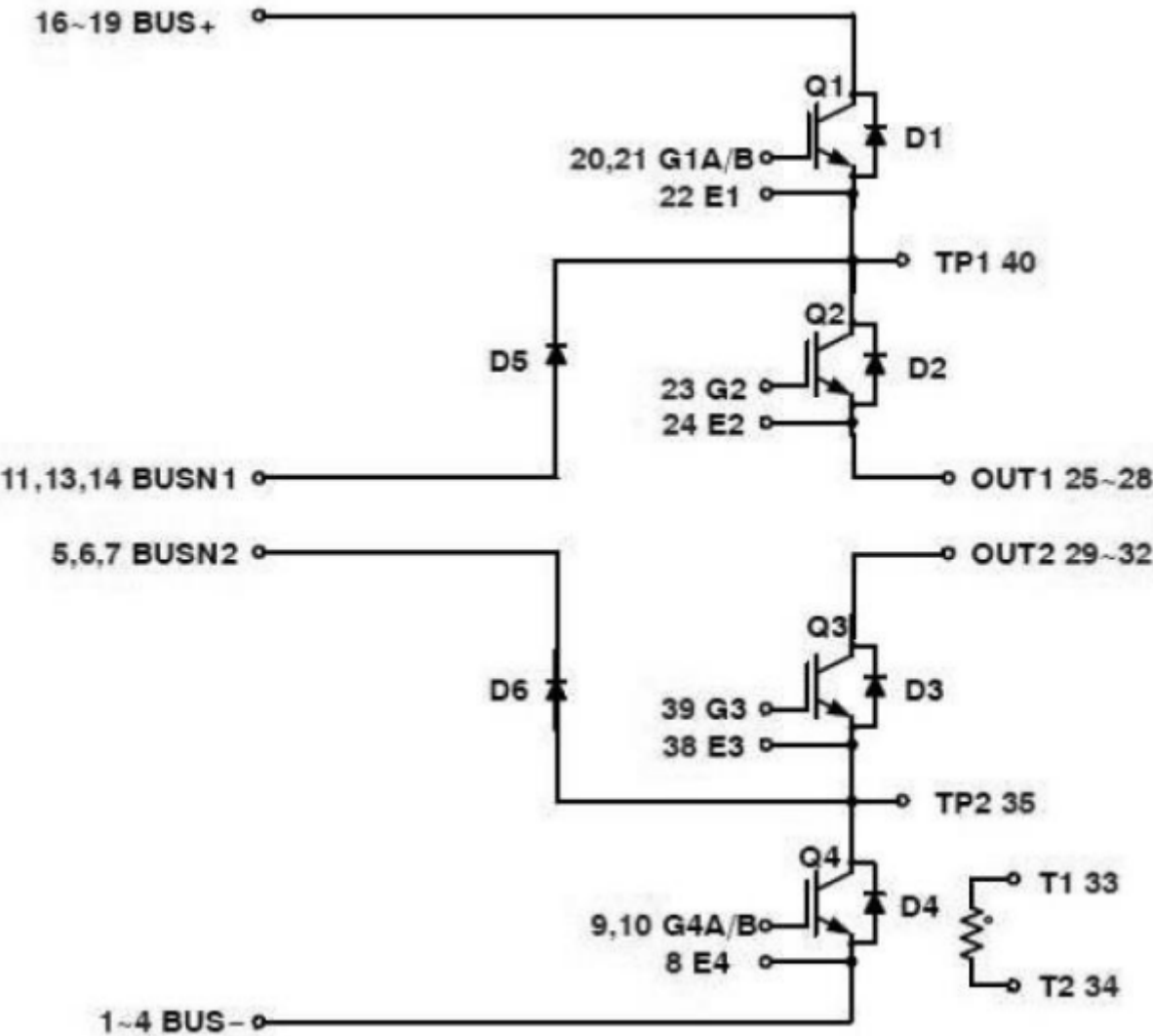
Typical di/dt vs. IC



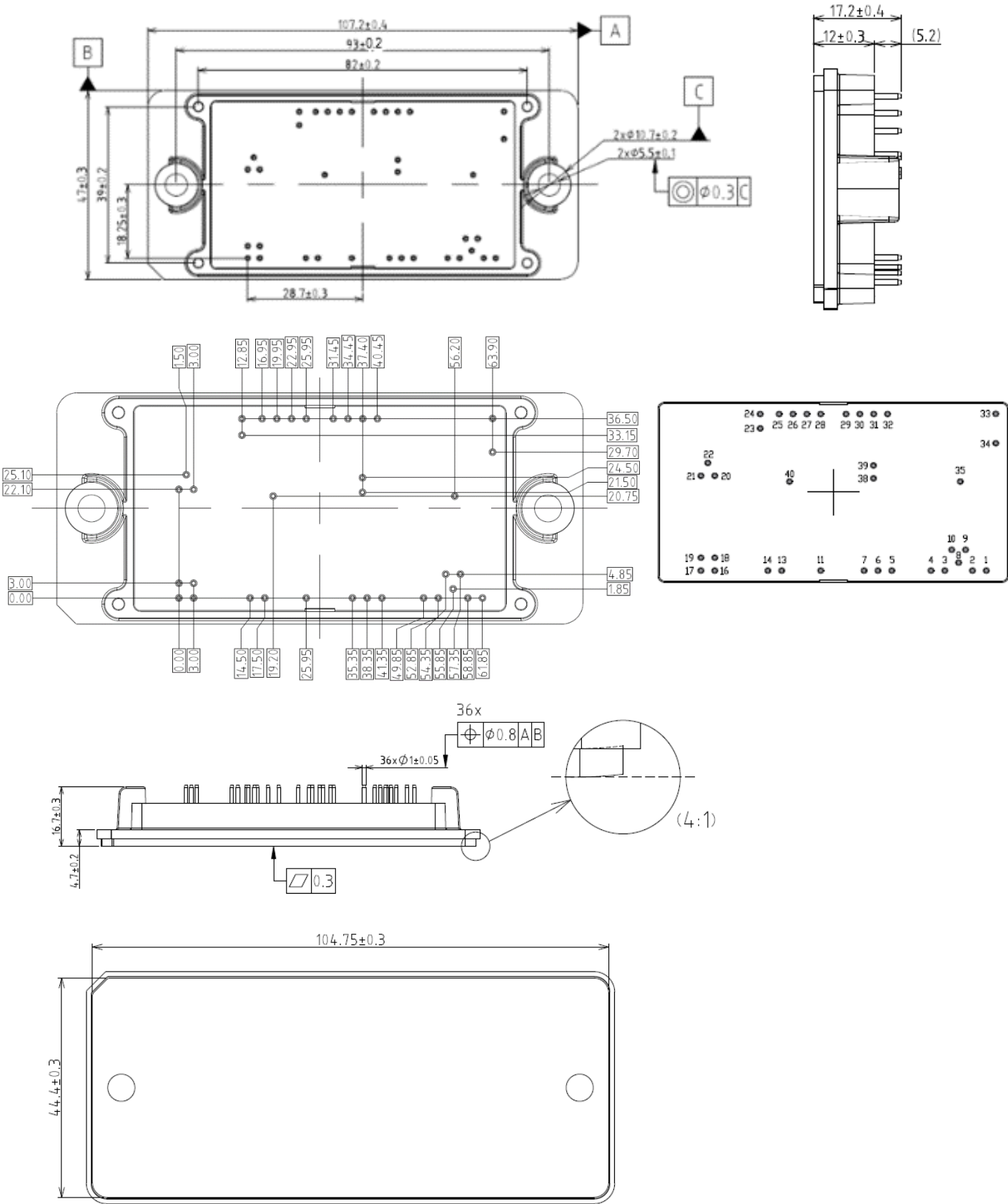
Typical Reverse Recovery Time vs. IC



Circuit diagram headline



Package outlines (Unit: mm)





**Terms & Conditions of usage**

- 1.The product specifications, characteristics, data, materials and structures given in this datasheet are subject to change without notice.
- 2.The information given in this datasheet shall in no event be regarded as a guarantee of conditions or characteristics. Marching-Power Technology Co., Ltd. does not warrant or assume any legal liability or responsibility for the accuracy and completeness of any examples, hints or any typical values stated herein and/or any information regarding the application of the product.
- 3.This datasheet is only used as a reference for customers to apply our products, Marching-Power Technology Co., Ltd. does not undertake to permit the use of intellectual property rights or any third-party property rights related to the product information described in this datasheet.
- 4.Although Marching-Power Technology Co., Ltd. is committed to enhancing product quality and reliability, all semiconductor products still have a probability of failure. When using Marching-Power semiconductor products in your equipment, you are requested to take adequate safety measures to prevent the equipment from causing accidents or events including but not limited to physical injury, fire or damage to other property if any of the products become faulty.
- 5.The products introduced in this datasheet are electrostatic sensitive devices and must be protected against static electricity during device installation, testing, packaging, storage and transportation.
6. Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.
- 7.Do not use the products introduced in this datasheet in equipment or systems that requiring strict reliability or/and may directly endanger human life such as medical, life-saving, life-sustaining, space equipment, aeronautic equipment, nuclear equipment submarine repeater equipment and equivalents to strategic equipment (without limitation).
- 8.No part of this datasheet may be disseminated and reproduced in any form or by any means without prior written permission from Marching-Power Technology Co., Ltd.
- 9.The data contained in this datasheet is exclusively intended for use by professional technicians only. It is the responsibility of the customer's own technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to corresponding application. If you have any question about any portion in this datasheet, contact Marching-Power Technology Co., Ltd. before using the product. Marching-Power Technology Co., Ltd. shall not be liable for any injury caused by any use of the products not in accordance with instructions set forth herein.

序号 Item	日期 Date	变更记录及描述 Change History Description	版本序号 Rev. item	经办人 Responsibility
1	2023.8.17	初版规格书发布，版本为V1.0	2023 8 Ver1.0	梁华文
2	2323.9.20	更新曲线图。	2023 9 Ver1.1	梁华文